

DWG. NO. SD 87256-**-91
 CAD FILE S8725691.DGN

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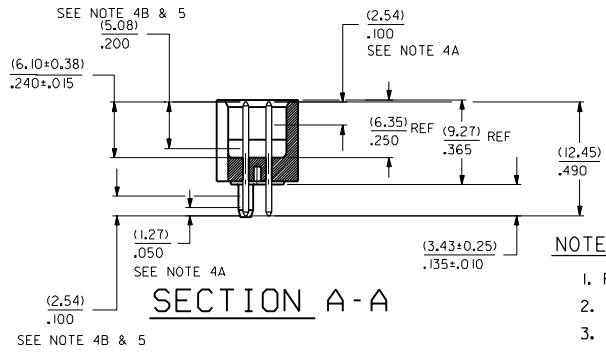
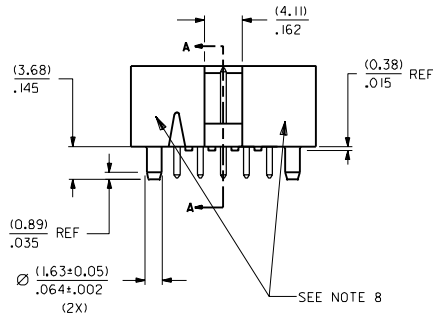
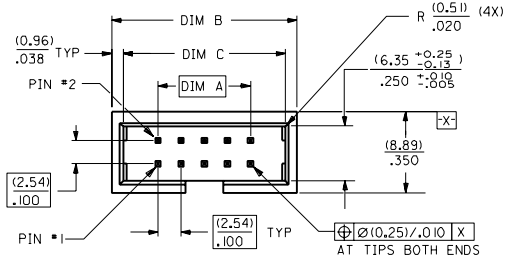
DO NOT SCALE DRAWING

PART NUMBERS	CKT SIZE	DIM A	DIM B $\begin{smallmatrix} +0.20 \\ -0 \end{smallmatrix}$	DIM C	DIM D
87256-3491	34	(40.64)/1.600	(50.18)/1.975	(48.26)/1.900	(45.72)/1.800

PART NUMBER LEGEND

87256 - * * 9 1

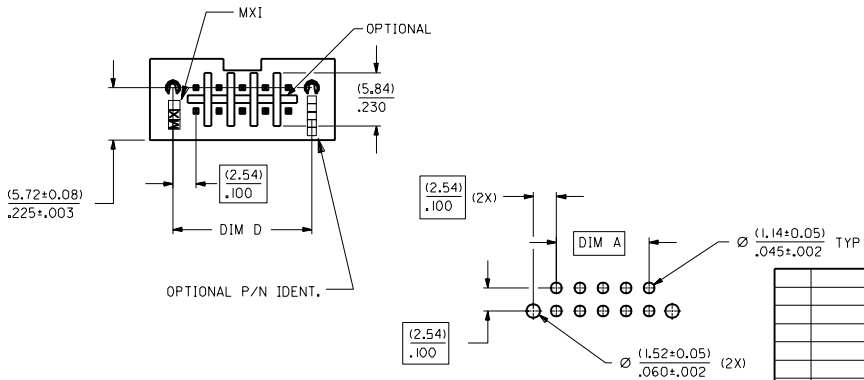
CKT SIZE
 ASSEMBLY OPTION
 91 - BEGIE



NOTES :

- PIN PUSHOUT FORCE (0.9072 KG)/2 LBS MIN.
- PRODUCT SPECIFICATION #70246 APPLIES.
- WAFER TO BE FLAT WITHIN (0.03MM/CM)/.003IN/IN.
- DIMENSIONS FOR PLATING LOCATIONS : A - MEASURE POINT FOR THICKNESS.
 B - MINIMUM COVERAGE.
- GOLD END OF PIN UNLESS OVERALL PLATED.
- FINISH : (PER ES-88)
 0.13um/5u" MIN GOLD FLASH OVER 1.02um/40u" MIN, PD/Ni IN SELECTED AREA AND 2.5um/100u" MIN, TIN/LEAD IN SELECTED AREA OVER 1.27um/50u" MIN NICKEL OVERALL
- FOR ILLUSTRATION PURPOSE A IO CKT IS SHOWN.
- OPTIONAL LOCATION FOR WEEK/YEAR STAMP IF REQUIRED BY CUSTOMER

(MM)
 INCH



RECOMMENDED PCB PATTERN

				MATERIAL : WAFER : HIGH TEMP. THERMOPLASTICS PINS : (0.64)/.025 SO CU ALLOY		MOLEX F.E.M.L South SHEET 1 OF 1	
				FINISH :		GENERAL TOLERANCES ± 0.20/.008	
REVISE PER ECN* S2486				S2486	JACK SK	920429	DWG. NO. SD 187256-**-91
LTR	REVISION RECORD	ECN	DR	CHK	DATE	DRAWN BY KHO O L 900803	CHK'D BY MAX LAI 901128
REVISE ONLY ON CAD SYSTEM						APPR'D BY ROY WONG	SCALE 2:1
						TITLE : C-GRID, SHROUDED WAFER SLOTTED, WITH IN-LINE POLARIZATION PEGS	